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CLAIMS

WHAT IS CLAIMED IS:

1. A method of sealing an interface, the method comprising:
 - 5 providing a sealant material;
 - locating the sealant material adjacent to the interface;
 - exposing the sealant material to an elevated temperature such that the sealant material flows adjacent the interface; and
 - 10 curing the sealant material to seal the interface.
2. A method as in claim 1 wherein the sealant material includes:
 - i. an epoxy resin;
 - 15 ii. an epoxy/elastomer adduct;
 - iii. a rheology modifier selected from an olefinic, a styrenic, an acrylic, an unsaturated carboxylic acid or an ester of a carboxylic ester;
 - iv. a curing agent; and
 - v. a filler.
3. A method as in claim 1 wherein the interface is created by two panels
20 of an automotive vehicle.
4. A method as in claim 3 further comprising:

prior to exposing the sealant material to an elevated temperature, coating a surface of the sealant material with a curing agent or curing agent accelerator for
25 hardening the surface of the sealant material.
5. A method as in claim 3 further comprising:

prior to exposing the sealant material to an elevated temperature, coating or spraying a liquid material upon a surface of the sealant material such that the liquid
30 material cures, hardens and coats the surface of the material.
6. A method as in claim 3 wherein the step of providing the sealant material includes coextruding a layer of first material with a mass of the sealant material and wherein the layer of first material is configured to maintain a higher

viscosity during the exposing step or the layer of first material is configured to cure faster than the sealant material during the curing step.

7. A method as in claim 3 wherein the exposing step and the curing step
5 are at least partially simultaneous and the sealant material is thermoset upon curing.

8. A method as in claim 3 wherein the sealant material includes an
ingredient such that the sealant material, during the exposing step, maintains a
surface energy that is no more than 25% greater or less than the surface energy of
10 the panels at the interface.

9. A method as in claim 3 wherein the sealant material is configured to,
during the exposing step, maintain a viscosity of below about 5000 centipoise for
between about 15 seconds and about 5 minutes.
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10. A method as in claim 9 wherein the sealant material includes an
encapsulated curing agent or curing agent accelerator.

11. A method as in claim 3 wherein the sealant material is located upon a
20 surface of one of the panels, but spaced away from the interface, and, during the
exposing step flows to cover the interface.

12. A method as in claim 3 wherein the sealant material is attached to a
trim piece during locating of the sealant material adjacent the interface.
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13. A method as in claim 3 wherein the sealant material includes magnetic
particles for assisting in locating the sealant material adjacent the interface.

14. A method of sealing an interface, the method comprising:
30 providing a sealant material;
locating the sealant material adjacent to the interface, the sealant material
including pieces of blocking material;;
exposing the sealant material to an elevated temperature such that the
sealant material flows adjacent the interface wherein the pieces of blocking material

prevent bubbles from penetrating through the sealant material to an outwardly facing surface of the sealant material; and
curing the sealant material to seal the interface.

5 15. A method as in claim 14 wherein the pieces are selected from flakes or platelets.

 16. A method as in claim 14 wherein the pieces are formed at least partially of PTE, polyamide, glass or ceramic.

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 17. A method of sealing an interface of a substrate, the method comprising:

 providing a sealant material including a contact surface;
 locating the sealant material adjacent to the interface such that the contact
15 surface contacts a first portion of the surface of the substrate;
 exposing the sealant material to an elevated temperature such that the sealant material flows adjacent the interface and contacts a second portion of the surface of the substrate progressively outward from the first portion; and
 curing the sealant material to seal the interface.

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 18. A method as in claim 17 wherein the sealant material has a U-shaped cross-section.

 19. A method as in claim 17 wherein the sealant material, upon placement
25 adjacent the interface, has a cantilevered portion.

 20. A method as in claim 17 wherein the sealant material has braided configuration.

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